

**AMENDMENTS TO THE SPECIFICATION:**

Please REPLACE paragraph no. **[0001]** on page 1 of the Specification with the following new paragraph:

**[0001]** This is a Continuation-In-Part Application of U.S. Patent Application Serial No. 09/986,390, now U.S. Patent No. 6,790,296, and International Application No. PCT/JP02/12033, now abandoned, the contents of which applications are incorporated herein by reference.

Please REPLACE paragraph no. **[0253]** on page 137 of the Specification with the following amended paragraph:

**[0253]** The melt flow rates (MFR) of the compounds representing Examples Nos. 1 to 3 and Comparative Example No. 1 were evaluated with a melt indexer. The evaluation conditions included a nozzle diameter of about 2.095 mm, an extrusion load of about 5 kgf/cm<sup>2</sup>, and melting temperatures of about 240 °C, about 260 °C and about 280 °C. It should be noted that the higher the MFR value of a compound, the better the flowability of the compound. The results are shown in the following Table 9.